2SC2206

Silicon NPN epitaxial planar type

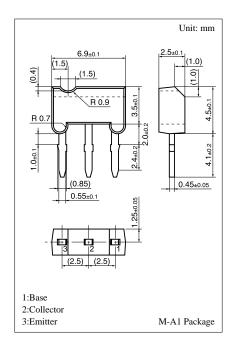
For high-frequency amplification Complementary to 2SA1254

Features

- Optimum for RF amplification of FM/AM radios.
- High transition frequency f_T.
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	30	V
Collector to emitter voltage	V_{CEO}	20	V
Emitter to base voltage	C_{EBO}	5	V
Collector current	I_{C}	30	mA
Collector power dissipation	P_{C}	400	mW
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	−55 ~ +150	°C

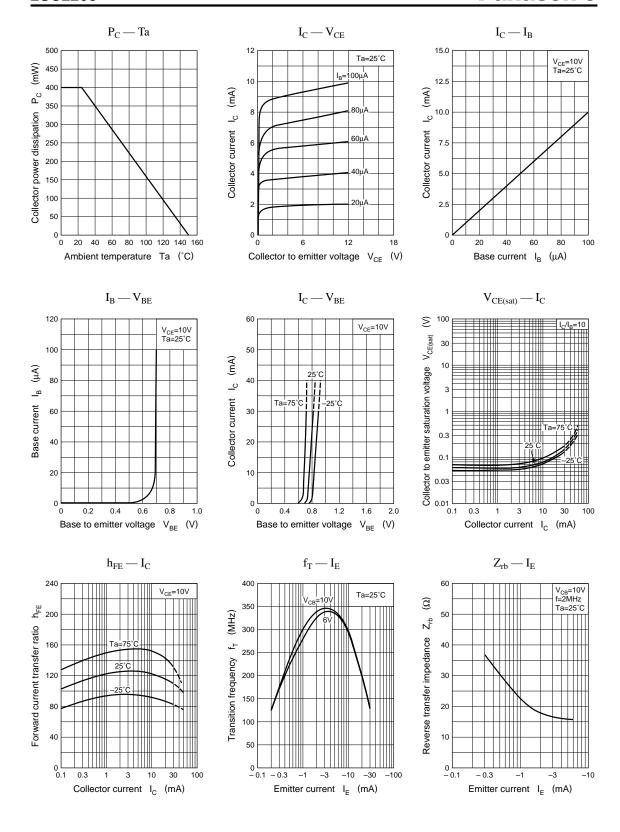


Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V _{CBO}	$I_{\rm C} = 10\mu{\rm A}, I_{\rm E} = 0$	30			V
Collector to emitter voltage	V _{CEO}	$I_C = 1 \text{mA}, I_B = 0$	20			V
Emitter to base voltage	V _{EBO}	$I_E = 10\mu A, I_C = 0$	5			V
Forward current transfer ratio	h _{FE} *	$V_{CB} = 10V, I_{E} = -1mA$	70		220	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 10$ mA, $I_B = 1$ mA		0.1		V
Base to emitter voltage	V _{BE}	$V_{CE} = 10V, I_{C} = 1mA$		0.7		V
Transition frequency	f_T	$V_{CB} = 10V, I_E = -1mA, f = 200MHz$	150	300		MHz
Noise figure	NF	$V_{CB} = 10V, I_E = -1mA, f = 5MHz$		2.8	4	dB
Common emitter reverse transfer capacitance	C _{re}	$V_{CE} = 10V, I_{C} = 1mA, f = 10.7MHz$			1.5	pF
Reverse transfer impedance	Z _{rb}	$V_{CB} = 10V, I_{E} = -1mA, f = 2MHz$			50	Ω

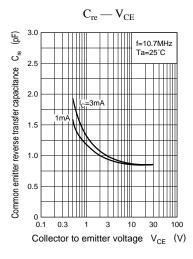
*hFE Rank classification

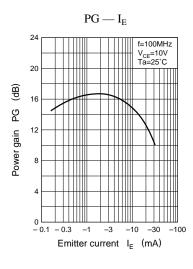
Rank	В	С
h_{FE}	70 ~ 140	110 ~ 220

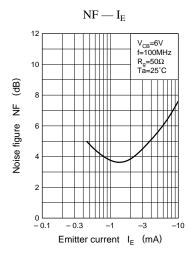


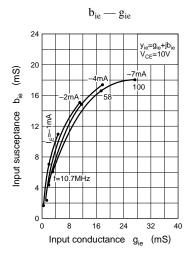
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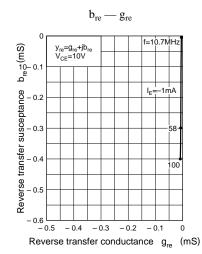
Panasonic 2SC2206

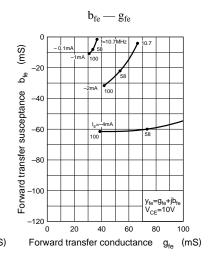


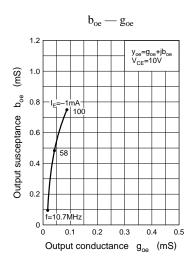












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